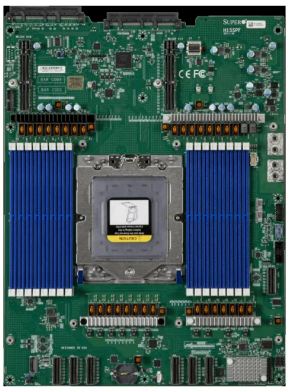
AMD EPYC (H15) | 2U Rackmount | Storage Server

Supermicro ASG-2117S7-NE332R

AMD EPYC (H15) · 2U Rackmount · Storage Server Server

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Form Factor	CPU
2U Rackmount	AMD EPYC™ 9006 SP7 Series Processors
GPU	**Memory**
1 double-width GPU	Max Memory (1DPC): Up to 4TB 8000MT/s ECC DDR5 RDIMM/3DS RDIMM

Key Features

- Single AMD EPYC™ 9006 Series Processor up to 600W with air cooling
- Up to 16 DIMMs supporting up to 4TB RDIMM DDR5-8000 in 1DPC or 4TB MRDIMM DDR5-12800 in 1DPC
- Gen6 Networking Support in both AOC and AIOM Format
- 1x PCIe 6.0 x16 TSFF AIOM (OCP 3.0) ;
- 2x PCIe 6.0 x16 FHHL slots;
- 1x PCIe 6.0 x16 FHFL Double-Width slot;
- 1x PCIe 4.0 x4 DC-SCM
- Upto 32x Hot Pluggable E3.S or E3.L Drive Slots in Front, and 2x Hot Pluggable 80mm M.2 slots in rear
- 2 Redundant 2000W Titanium power supplies
- 2U Rackmount chassis with 30.6" (778 mm) depth

Form Factor	2U Rackmount
Platform	AMD EPYC (H15)
CPU	Single processor(s) AMD EPYC™ 9006 SP7 Series Processors
Max GPU Count	1 double-width GPU
Memory	Slot Count: 16 DIMM slots Max Memory (1DPC): Up to 4TB 8000MT/s ECC DDR5 RDIMM/3DS RDIMM
Drive Bays	Option A: Total 32 bays32 front hot-swap E3.S 1T PCIe 6.0 x2 NVMe drive bays
Fans	6 counter-rotating 60x60x56mm Fan(s)
Power Supply	2x 2700W Redundant (1 + 1) Titanium Level (96%) power supplies

Full Specifications — ASG-2117S7-NE332R

Product SKUs

Part numbers	ASG-2117S7-NE332R

Motherboard

Motherboard	A+ Motherboard® H15SPF

Processor

CPU	Single processor(s) AMD EPYC™ 9006 SP7 Series Processors
Core Count	Up to 256C/512T
Note	Supports up to 600W TDP CPUs (Air Cooled)

GPU

Max GPU Count	1 double-width GPU

System Memory

Memory	Slot Count: 16 DIMM slots Max Memory (1DPC): Up to 4TB 8000MT/s ECC DDR5 RDIMM/3DS RDIMM Max Memory (1DPC): Up to 4TB 12800MT/s ECC DDR5 MRDIMM View Memory Options
Memory Voltage	1.1V

On-Board Devices

SAS	SAS (12Gbps) via Broadcom® 3808; RAID 0/1 support
IPMI	Support for Intelligent Platform Management Interface v.2.0 IPMI 2.0 with virtual media over LAN and KVM-over-LAN support

Input / Output

LAN	1 RJ45 1 GbE Dedicated BMC LAN port
USB	2 USB 3.0 ports (rear)
Video	1 VGA port
TPM	1 TPM header

System BIOS

BIOS Type	AMI 64MB SPI Flash EEPROM

BIOS Features	Plug and Play (PnP) UEFI 2.8 USB Keyboard support ACPI 6.5 SMBIOS 3.7 or later

Management

Software	SuperCloud Composer® (SCC) Supermicro Server Manager (SSM) Super Diagnostics Offline (SDO) KVM with dedicated LAN IPMI 2.0 Supermicro Thin-Agent Service (TAS) SuperServer Automation Assistant (SAA) New! IPMIView
Power configurations	ACPI/APM Power Management Power-on mode control for AC power loss recovery Power button override mechanism,

Security

Hardware	Trusted Platform Module (TPM) 2.0 Silicon Root of Trust (RoT) – NIST 800-193 Compliant
Features	Cryptographically Signed Firmware Secure Boot Secure Firmware Updates Automatic Firmware Recovery Supply Chain Security: Remote Attestation Runtime BMC Protections System Lockdown

PC Health Monitoring

Fan	Fans with tachometer monitoring Pulse Width Modulated (PWM) fan connectors Status monitor for speed control
Temperature	Monitoring for CPU and chassis environment Thermal Control for fan connectors
Voltage	System temperature, Memory temperature, CPU temperature, 3.3V standby, +5V standby, +5V, +3.3V, +12V, CPU thermal trip support

Certifications

Operating Systems	Venice: Oracle Linux 10.2, RHEL 10.2 View all OS Compatibility and Certification Matrix

Chassis

Form Factor	2U Rackmount
Model	CSE-256E3-R000NDP

Dimensions and Weight

Height	3.47" (88 mm)
Width	17.25" (438 mm)
Depth	30.7" (780 mm)
Package	9.4" (H) x 23.5" (W) x 43.2" (D)
Weight	Gross Weight: 83.78 lbs (38 kg) Net Weight: 61.73 lbs (28 kg)
Available Color	Silver

Expansion Slots

PCI-Express (PCIe) Configuration	Option A*2 PCIe 6.0 x16 (in x16) FHFL slots 2 PCIe 6.0 x16 (in x16) FHFL slots Option B*1 PCIe 6.0 x16 (in x16) FHFL double-width slot 1 PCIe 6.0 x16 (in x16) AIOM double-width slot (OCP 3.0 compatible) 1 PCIe 6.0 x16 (in x16) FHFL double-width slot 1 PCIe 6.0 x16 (in x16) AIOM double-width slot (OCP 3.0 compatible) Default1 PCIe 6.0 x16 (in x16) FHHL double-width slot 1 PCIe 6.0 x16 (in x16) AIOM slot (OCP 3.0 compatible) 1 PCIe 6.0 x16 (in x16) FHHL double-width slot 1 PCIe 6.0 x16 (in x16) AIOM slot (OCP 3.0 compatible) (*Requires additional parts, please see the optional parts list for details. For more details on PCIe slot configuration options, please refer to the system callout images above.)
M.2	2 M.2 PCIe 4.0 x4 NVMe slots (M-key)

Drive Bays / Storage

Drive Bays Configuration	Option A: Total 32 bays32 front hot-swap E3.S 1T PCIe 6.0 x2 NVMe drive bays 32 front hot-swap E3.S 1T PCIe 6.0 x2 NVMe drive bays Option B: Total 16 bays16 front hot-swap E3.L 1T PCIe 6.0 x4 NVMe drive bays 16 front hot-swap E3.L 1T PCIe 6.0 x4 NVMe drive bays
M.2	2 M.2 PCIe 4.0 x4 NVMe slots (M-key 2280/22110)

System Cooling

Fans	6 counter-rotating 60x60x56mm Fan(s)
Air Shroud	1 Air Shroud

Power Supply

2x 2700W Redundant (1 + 1) Titanium Level (96%) power supplies

Dimension (WxHxL)	73.5 x 40 x 265 mm
Input	1000W: 100-127Vac / 50-60Hz 1800W: 200-220Vac / 50-60Hz 1980W: 220-230Vac / 50-60Hz 2000W: 230-240Vac / 50-60Hz 2000W: 220-240Vac / 50-60Hz (for UL only) 2000W: 230-240Vdc / 50-60Hz (for CQC only)
+12V	Max: 83A / Min: 0A (100Vac-127Vac) Max: 150A / Min: 0A (200Vac-220Vac) Max: 165A / Min: 0A (220Vac-230Vac) Max: 166A / Min: 0A (230Vac-240Vac)
12V SB	Max: 3.5A / Min: 0A
Output Type	Backplanes (gold finger)

Operating Environment

Environmental Spec.	Operating Temperature: 10°C to 35°C (50°F to 95°F) Non-operating Temperature: -40°C to 70°C (-40°F to 158°F) Operating Relative Humidity: 8% to 90% (non-condensing) Non-operating Relative Humidity: 5% to 95% (non-condensing)

Environmental / Recycling

Recycle	Return Server-End of Life Product